

Component - Wiring, Printed (ZPMV2, ZPMV3, ZPMV8, ZPMV9)

TABLE B - SAMPLE SELECTION GUIDE

Sample Group	ANSI Type or Generic	Model	Report date	Additional info	Bond Strength Test
1	FR-4.0				
		JLC-1	2016-02-04	-	56-Day
		JLC-2	2016-02-03	-	56-Day
		JLC-3 (ASPl) (Notel)	2024-02-04	-	10-Day
		JLC-4 (ASPl)	2024-02-05	-	10-Day
2	No ANSI				
		JLC-5 (ASPl)	2024-02-04	-	56-Day
		JLC-6 (ASPl)	2024-02-04	-	10-Day
		JLC-7 (ASPl)	2024-02-04	-	10-Day
		JLC-8 (ASPl)	2024-03-07	-	10-Day
		JLC-9 (ASPl)	2024-03-07	-	10-Day

Component - Wiring, Printed (ZPMV2, ZPMV3, ZPMV8, ZPMV9)

INDEX TO FOOTNOTES:

(ASP1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27
Thermal Stress Assembly Simulation

(Note1) - When the external copper thk range from 102mic to 140mic,
the Min Width and Min edge Width is 0.30mm